



THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Application of:

Thomas H. Osterheld

Serial No.: 09/826,419

Confirmation No.: 5039

Filed:

April 5, 2001

For:

GRID RELIEF IN CMP POLISHING PAD TO

ACCURATELY MEASURE PAD WEAR, PAD PROFILE AND PAD WEAR PROFILE

Assistant Commissioner for Patents Washington, D.C. 20231

Dear Sir:

Group Art Unit: 3723

Examiner:

David B. Thomas

CERTIFICATE OF MAILING 37 CFR 1.8

I hereby certify that this correspondence is being deposited on 2002 with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant

Commissioner for Patents, Washington, D.C. 2023.

415/02

Signature

RESPONSE TO OFFICE ACTION DATED JANUARY 15, 2002

In response to the Office Action dated January 15, 2002, having a shortened statutory period for response set to expire on April 15, 2002, please enter the following amendments and reconsider the claims pending in the application for reasons discussed below. The Commissioner is authorized to charge \$420.00 to Deposit Account No. 20-0782/AMAT/3415/BTP for the addition of five independent claims.

IN THE CLAIMS:

Please amend the following claims:

1. (Amended) A chemical mechanical polishing pad having a plurality of reliefs in a main polishing surface for determining wear of the pad, wherein the reliefs are disposed in a predetermined pattern such that the wear of the pad is determinable as a function of pad radius.